



**Product Model 6920:**  
Automatic MCM/Flip Chip Die Attach System

**MAT – MicroAssembly Technologies, Ltd.**  
**Product Model 6920**

New generation Fully Automatic MCM and Flip Chip Die Attach System. Developed for high volume production of Multi Chip Modules including active chip & wire and flip chip components, as well as passive components.

Magazine to Magazine or In-Line configuration. Based on the unique Two Head architecture that ensures highest Flexibility and Throughput in parallel with smallest Footprint.

Handles up to Seventy Waffle/Gel packs, up to Forty Reel Feeders or up to TEN different 8" Wafers at a time.

Full Flip Chip capability including die pickup from wafer, waffle/Gel pack and surf tape, chip flipping, bump fluxing and high accuracy alignment based on Up Looking Vision.

Dispensing of single/multi dot and shape patterns.

Library of complex pre-taught dispense shapes.

Advanced vision algorithms ensure accurate alignment of substrates and active or passive components as well as detection of ink dots.

Programmable accurate Bond Line Thickness control.

Unique one pass die stacking capability.

NEW - Eutectic capability based on heat and programmable scrubbing.

